

SOT2139-1

LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.65 mm pitch, 9 mm x 9 mm x 1.3 mm body

19 May 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA169
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	28-04-2021
Manufacturer package code	98ASA01774D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.85	9	9.15	mm
package width	8.85	9	9.15	mm
package height	-	1.3	1.43	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	169	-	



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2 Package outline

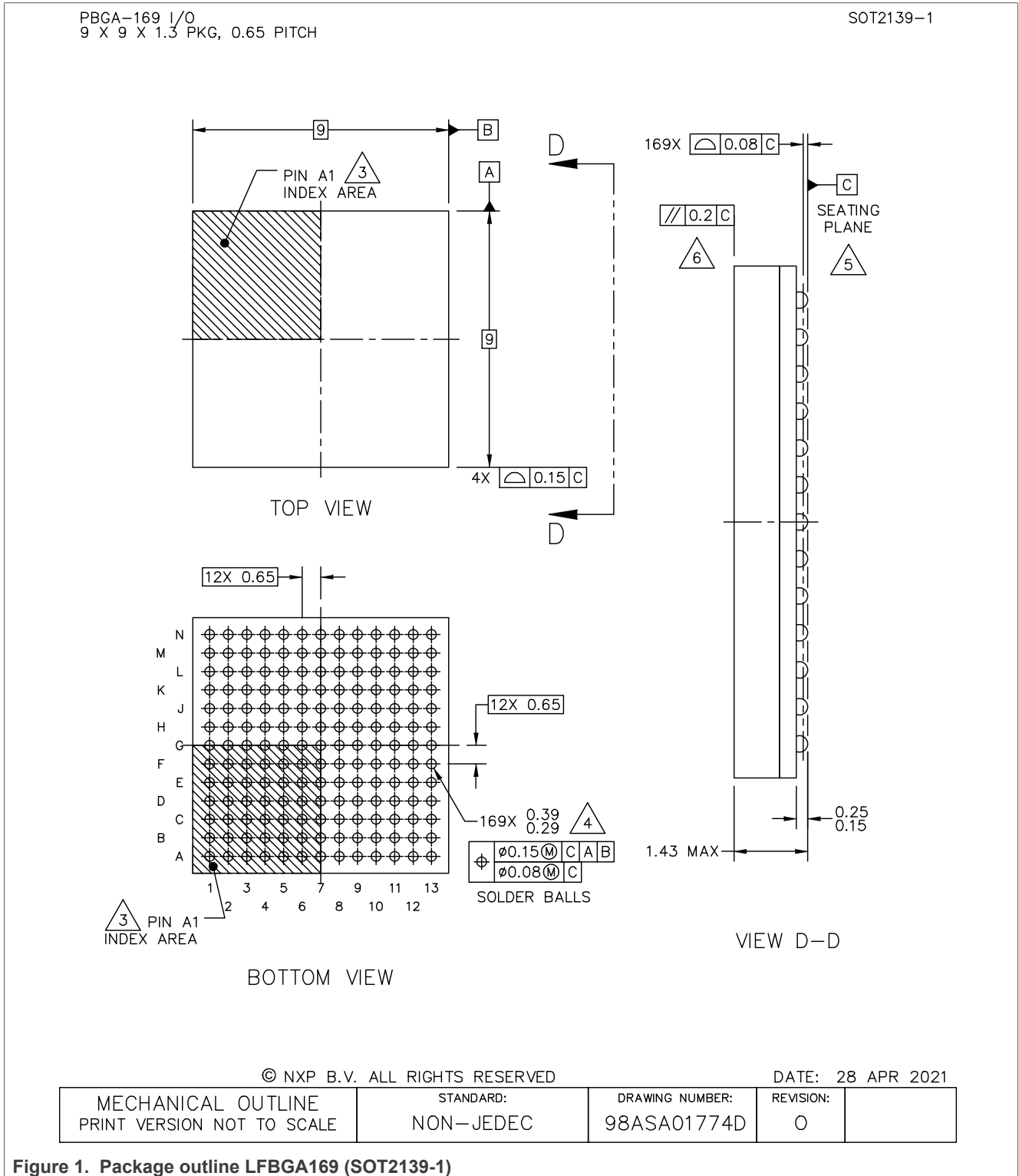
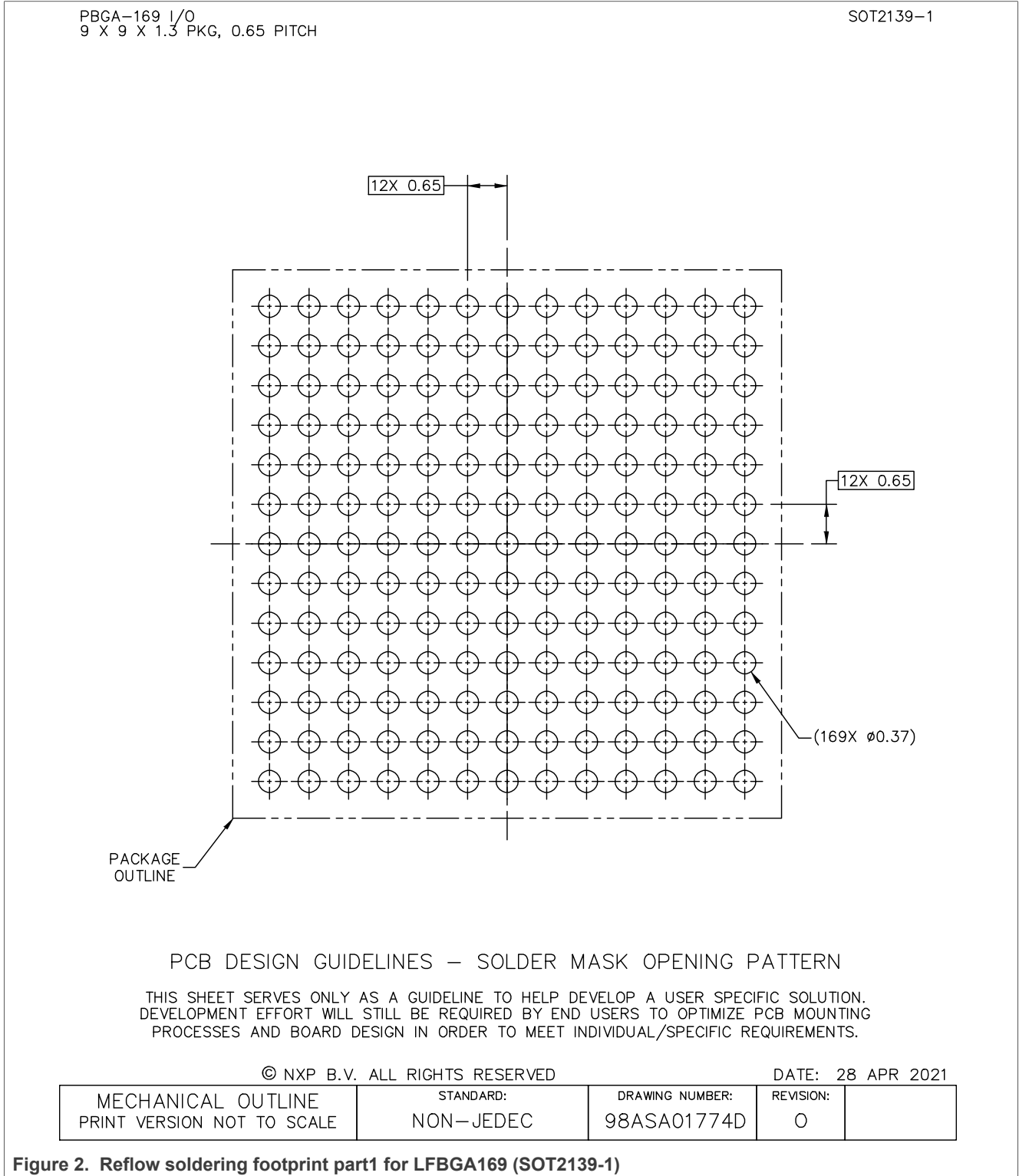


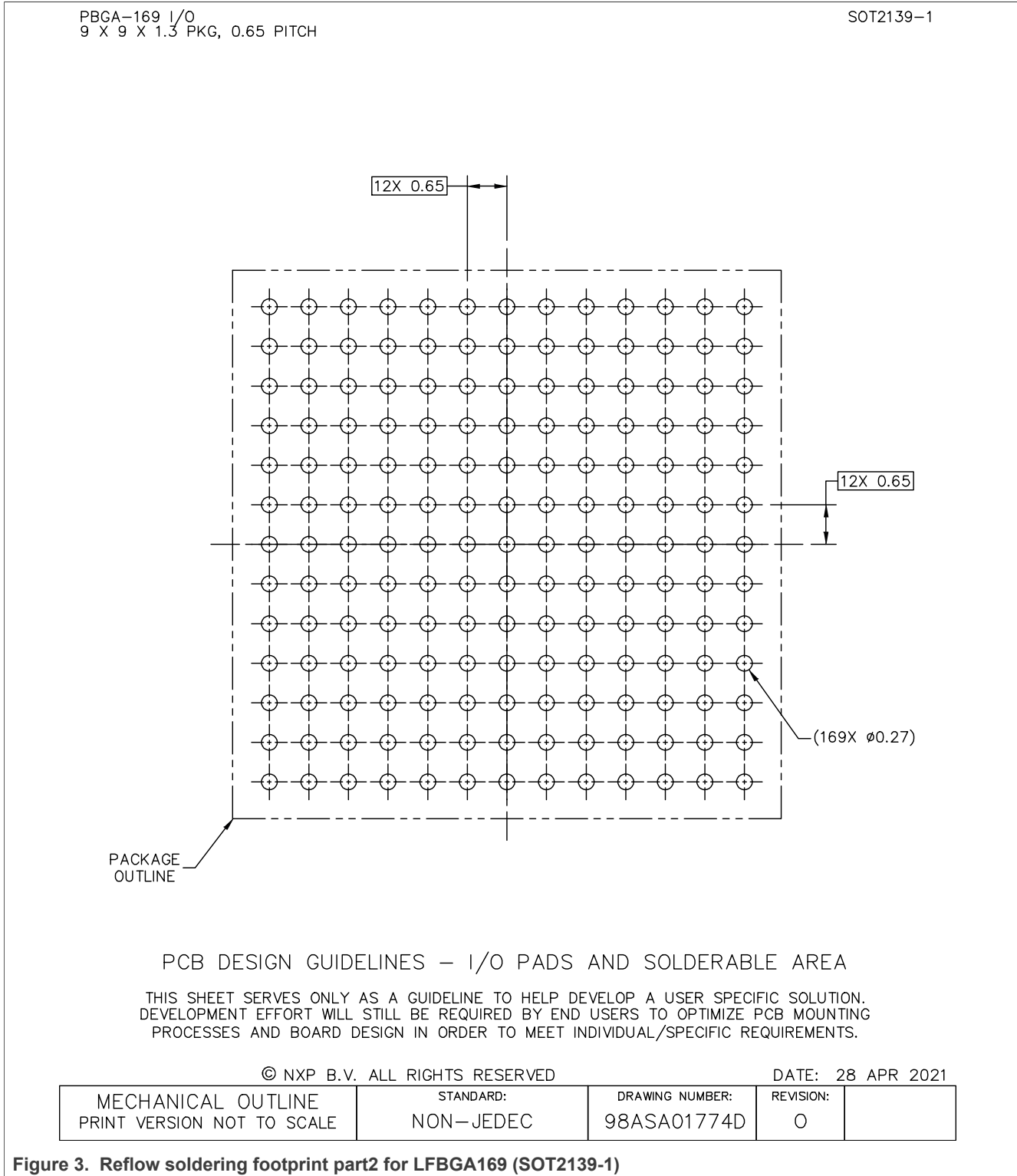
Figure 1. Package outline LFBGA169 (SOT2139-1)

LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.65 mm pitch, 9 mm x 9 mm x 1.3 mm body

3 Soldering



LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.65 mm pitch, 9 mm x 9 mm x 1.3 mm body



LFBGA169, low-profile fine-pitch ball grid array package, 169 terminals, 0.65 mm pitch, 9 mm x 9 mm x 1.3 mm body

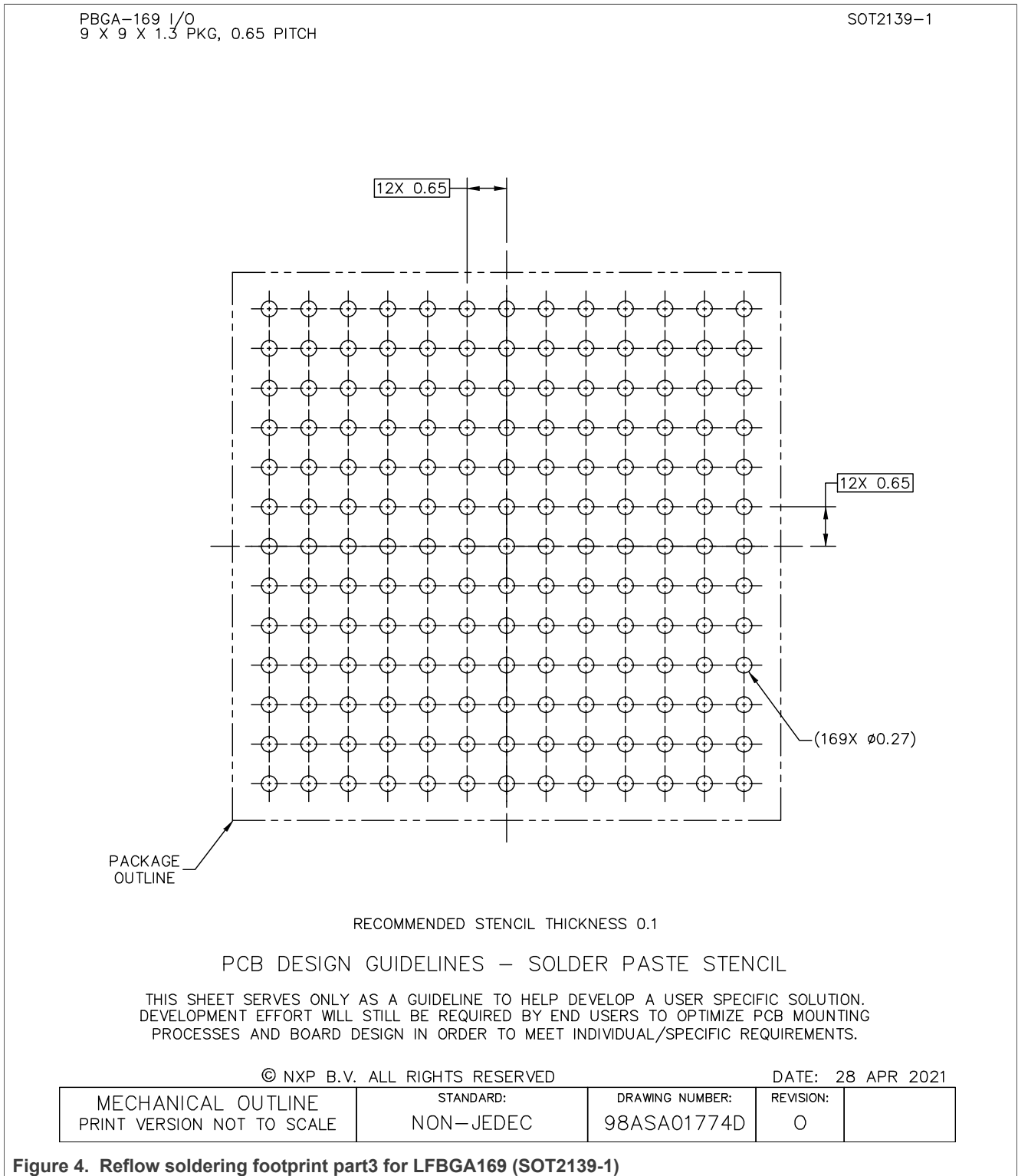


Figure 4. Reflow soldering footprint part3 for LFBGA169 (SOT2139-1)

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PBGA-169 I/O
9 X 9 X 1.3 PKG, 0.65 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 28 APR 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01774D	REVISION: 0	
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Figure 5. Package outline note LFBGA169 (SOT2139-1)

4 Legal information

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Contents

1	Package summary	1
2	Package outline	2
3	Soldering	3
4	Legal information	7